



2858

PATENT
YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : D.Y.Shih, et al.
Serial Number : 09/254,769
Filing Date : March 11, 1999
Examiner : V. Nguyen
Group Art Unit : 2858
For : WAFER SCALE HIGH DENSITY
PROBE ASSEMBLY,
APPARATUS FOR USE THEREOF
AND METHODS OF
FABRICATION THEREOF

Honorable Commissioner of Patents
and Trademarks
Washington, D.C. 20231

Sir:

In response to the Official Action dated May 27, 2003, please amend the above-identified application as follows:

Amend the Claims as set forth hereinafter.

Insert the enclosed Abstract of the Disclosure into this case.

RECEIVED
SEP - 5 2003
TECHNOLOGY CENTER 2800